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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/651,813	08/28/2003	Young-Hee Song	9903-078	9556
20575 7	7590 03/27/2006	EXAMINER		
	HNSON & MCCOL RISON STREET, SUIT	WILLIAMS, ALEXANDER O		
PORTLAND,		ART UNIT	PAPER NUMBER	
			2826	
			DATE MAILED: 03/27/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)			
Office Action Summary		10/651,813	SONG ET AL.	6		
		Examiner	Art Unit	—(M		
		Alexander O. Williams	2826			
Period fo	The MAILING DATE of this communication app or Reply	ears on the cover sheet with the c	orrespondence address -	-		
WHIC - Exter after - If NO - Failu Any r	CORTENED STATUTORY PERIOD FOR REPLY CHEVER IS LONGER, FROM THE MAILING DAISIONS of time may be available under the provisions of 37 CFR 1.13 SIX (6) MONTHS from the mailing date of this communication. period for reply is specified above, the maximum statutory period we to reply within the set or extended period for reply will, by statute, eply received by the Office later than three months after the mailing and patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be timulating and will expire SIX (6) MONTHS from cause the application to become ABANDONE	N. nely filed the mailing date of this communica D (35 U.S.C. § 133).			
Status						
2a) <u></u> □	Responsive to communication(s) filed on <u>12 January 2006</u> . This action is FINAL . 2b) This action is non-final. Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
,_	closed in accordance with the practice under E					
Dispositi	on of Claims					
5)⊠ 6)⊠ 7)□	Claim(s) <u>1,3,4,6-11,24-30,33,34,36-38,40,42 a</u> 4a) Of the above claim(s) is/are withdrav Claim(s) <u>1,3,4 and 6-11</u> is/are allowed. Claim(s) <u>24 to 30, 33, 34, 36 to 38, 40, 42 and</u> Claim(s) is/are objected to. Claim(s) are subject to restriction and/or	vn from consideration. <u>47 to 51</u> is/are rejected.	plication.			
Applicati	on Papers					
10)□ 11)□	The specification is objected to by the Examine The drawing(s) filed on is/are: a) accomplicant may not request that any objection to the Replacement drawing sheet(s) including the correct The oath or declaration is objected to by the Example 25 U.S.C. 5 440	epted or b) objected to by the Eddrawing(s) be held in abeyance. See ion is required if the drawing(s) is obj	e 37 CFR 1.85(a). jected to. See 37 CFR 1.12			
-	ınder 35 U.S.C. § 119		4.0.			
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No. 10/192,800. 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 						
Attachmen		↑ □	(DTO 442)			
2) Notice 3) Information Paper	e of References Cited (PTO-892) se of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) r No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:				
J.S. Patent and T	rademark Office					

Art Unit: 2826

Serial Number: 10/651813 Attorney's Docket #: 9903-078

Filing Date: 8/28/2003; claimed foreign priority to 7/10/2001 and 1/18/2002

Applicant: Song et al.

Examiner: Alexander Williams

Applicant's Amendment filed 1/12/06 has been acknowledged.

Applicant's had election of the species of figure 18 (claims 1, 3, 4, 6-11, 24-30, 33, 34,36-38, 40, 42, 46, 47 and 48-51), filed 5/3/2004, has been acknowledged.

Claims 2, 5, 12-23, 31, 32, 35, 39, 41, 43-46, 52 and 53 have been cancelled.

Acknowledgment is made of applicant's claim for foreign priority under 35 U.S.C. 119(a)-(d). The certified copies has been filed in parent Application No. 10/192800, filed on 7/9/2002.

The disclosure is objected to because of the following informalities: This Applicant's being a divisional application to 10/192800, filed 7/9/2002 and now U.S. Patent # 6,6442,627, this related application information should be updated in this application specification.

Appropriate correction is required.

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Application/Control Number: 10/651,813

Art Unit: 2826

Claims 24 to 30, 33, 34, 36 to 38, 40, 42 and 47 to 51 are rejected under 35 U.S.C. 102(e) as being anticipated by Pflughaupt et al. (U.S. Patent Application Publication # 2006/0033216 A1).

Page 3

- 24. For example, in claim 24 and similar claims 36 and 47, Pflughupt et al. (figures 1-25) specifically figures 1-3 show a multi-chip package comprising: a first chip (first 20); and a second chip (second 20) formed over the first chip, the first chip includes: a bond pad-wiring pattern (inherent under 64) formed substantially in a center region of the first chip; and a pad-rearrangement pattern 40,36,38 directly contacting the bond pad-wiring pattern; and an insulating layer 76,74 formed on the pad-rearrangement pattern, wherein the pad-rearrangement pattern includes a first bond pad 22 disposed at an edge of the first chip, wherein the first bond pad is exposed through the insulating layer. 25. The multi-chip package of claim 24, Pflughupt et al. showing wherein the pad-rearrangement pattern includes a second bond pad, and wherein the first and second
- 26. The multi-chip package of claim 25, Pflughupt et al. showing wherein the padrearrangement pattern extends substantially from the center region of the first chip toward the edge of the first chip.

bond pads are respectively disposed along opposing edges of the first chip.

- 27. The multi-chip package of claim 24, Pflughupt et al. show wherein the bond padwiring pattern is formed on a first surface of the first chip, and wherein the second chip is mounted on the first surface of the first chip.
- 28. The multi-chip package of claim 27, Pflughupt et al. showing further comprising a spacer interposed between the first chip and the second chip.
- 29. The multi-chip package of claim 24, Pflughupt et al. further comprising a substrate **82** on which the first chip is mounted.
- 30. The multi-chip package of claim 29, Pflughupt et al. showing wherein the substrate **82** comprises a printed circuit board, a tape wiring substrate or a lead frame.
- 33. The multi-chip package of claim 24, Pflughupt et al. show wherein the first bond pad is disposed under the second chip.
- 34. The multi-chip package of claim 24, Pflughupt et al. showing wherein the first and second chips comprise the same type of chips.

Application/Control Number: 10/651,813

Art Unit: 2826

Applicant cannot rely upon the foreign priority papers to overcome this rejection because a translation of said papers has not been made of record in accordance with 37 CFR 1.55. See MPEP § 201.15.

Claims 1, 3, 4, 6-11 are allowed.

Response

Applicant's arguments filed 7/29/05 have been fully considered, but are moot in view of the grounds of rejections detailed above.

The listed references are cited as of interest to this application, but not applied at this time.

Field of Search	Date
U.S. Class and subclass:	6/24/04
257/686,685,734,777,784,786,728,724,725,698,690,203,	1/22/05
211,208	10/3/05
	3/16/06
Other Documentation:	6/24/04
foreign patents and literature in	1/22/05
257/686,685,734,777,784,786,728,724,725,698,690,203,	10/3/05
211,208	3/16/06
Electronic data base(s):	6/24/04
U.S. Patents EAST	1/22/05
	10/3/05
	3/16/06

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Alexander O Williams whose telephone number is (571) 272 1924. The examiner can normally be reached on M-F 6:30-7:00PM.

Art Unit: 2826

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272 1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

AOW 3/16/06

Primary Patent Examiner Alexander O. Williams